DECLARATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled METHOD AND STRUCTURE FOR REDUCING RESISTANCE OF A SEMICONDUCTOR DEVICE FEATURE, the specification of which:

\underline{X} is attached hereto.	
was filed on, as Application Serial No	
I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims.	
I acknowledge the duty to disclose information which is material to patentability of the subject matter claimed in this application as "materiality" is defined in Title 37 of the Code of Federal Regulations, § 1.56.	
I hereby claim the benefit of any earlier filing date in the United States to which I am entitled under Title 35 of the United States Code, § 120 and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35 of the United States Code, § 112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37 of the Code of Federal Regulations, § 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application.	

(Application Serial No.)

(Filing Date)

(Status)

Send correspondence to:

Kevin D. Martin, Reg. 37,882 Mail Stop 1-525 Micron Technology, Inc. 8000 S. Federal Way Boise, Idaho 83716 (208) 368-4516

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Title 18 of the United States Code, § 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of first or sole inventor: You

Yongjun J. Hu

Inventor's Signature:

Arst. Middle Initial Last)

Date:

Residence Address: 2571 S. Culpeper Ave

City, State, Country:

Boise, Idaho

United States of America

Citizenship:

United States of America Same as residence address

Post Office Address:

IN THE UNITED STATES PATENT OFFICE

In re Application of:	§ Atty. Docket: 2003-0930.00/US
Yongjun J. Hu	§ Certificate of Express Mailing (37 CFR § 1.10)
Serial No.: Not Assigned	Separation of Deposit:
Filed: Concurrently Herewith	
For: METHOD AND STRUCTURE FOR REDUCING RESISTANCE OF A SEMICONDUCTOR DEVICE FEATURE	

ELECTION UNDER 37 C.F.R. §§ 3.71 AND 3.73 AND POWER OF ATTORNEY

Mail Stop Patent Application Commissioner for Patents PO Box 1450 Alexandria, VA 22313-1450

Dear Sir:

The undersigned, being Assignee of the entire interest in the above-identified application by virtue of an Assignment recorded in the United States Patent and Trademark Office as set forth below or filed herewith, hereby elects, under 37 C.F.R. § 3.71, to prosecute the application to the exclusion of the inventor.

The Assignee hereby revokes any previous Powers of Attorney and appoints: Charles B. Brantley, II, Reg. No. 38,086; Michael L. Lynch, Reg. No. 30,871; Kevin D. Martin, Reg. No. 37,882; David J. Paul, Reg. No. 34,692; and Russell D. Slifer, Reg. No. 39,838, as its attorney or agent, with full power of substitution and revocation, to prosecute the application, to make alterations and amendments therein, to transact all business in the Patent and Trademark Office in connection therewith, to receive any Letters Patent, and for one year after issuance of such Letters Patent to file any request for a certificate of correction that may be deemed appropriate.

Pursuant to 37 C.F.R. § 3.73, the undersigned duly authorized designee of Assignee certifies that the evidentiary documents have been reviewed, specifically the Assignment to MICRON TECHNOLOGY, INC., referenced below, and certifies that to the best of my knowledge and belief, title remains in the name of the Assignee.

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<u>Assig</u>	nment:	Please direct all communications as follows:
<u>X</u>	Filed concurrently herewith for recording, a copy of which is attached hereto.	Kevin D. Martin MICRON TECHNOLOGY, INC. Mail Stop 1-525 8000 S. Federal Way Boise, ID 83716-9632 (208) 368-4516
	Previously recorded on:, at Reel:, Frame:	
	ACCICNI	CE. MICDON TECHNIOLOGY INC

ASSIGNEE: MICRON TECHNOLOGY, INC.

Date: 19,2007 Michael L. Lynch, Reg. No. 30,871 Chief Patent Counsel